

Part Number: 758888000

Series Number: 75888

Product Description: 2.00mm Pitch VHDM Board-to-Board Backplane Receptacle Power Module, Vertical, 8-Row, 3 Circuits, Gold (Au)

Selective 0.76µm Lead-Free

Status: Active

Product Category: Backplane Connectors

Documents & Resources

Drawings

Drawing 758888000_sd.pdf

Packaging Design Drawing PK-70873-0876-001.pdf

3D Models and Design Files

3D Model 758888000_stp.zip

Specifications

Product Specification PS-74031-999-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	©
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)8585-DC (23 Jan 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474

Part Details

General

Status	Active
Category	Backplane Connectors
Series	75888
Description	2.00mm Pitch VHDM Board-to- Board Backplane Receptacle Power Module, Vertical, 8-Row, 3 Circuits, Gold (Au) Selective 0.76µm Lead- Free
Application	Backplane
Comments	Backplane Receptacle Module, Power
Component Type	Power Receptacle
Product Family	VHDM Backplane Connectors and Cable Assemblies
Product Name	VHDM
UPC	822350147675

Electrical

Current - Maximum per Contact	10.0A
Data Rate	2.5 Gbps
Real Signals (per 25mm)	100
Shielded	No
Voltage - Maximum	120V AC (RMS)/DC

Physical

Circuits (Loaded)	3
Circuits (maximum)	3
Color - Resin	Black
Durability (mating cycles max)	200
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None

Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	1.519/g
Number of Columns	N/A
Number of Pairs	Open Pin Field
Number of Rows	8
Orientation	Vertical
Packaging Type	Tube
PC Tail Length	2.80mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.80mm
Pitch - Mating Interface	6.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.381µm
Polarized to PCB	Yes
Stackable	No
Temperature Range - Operating	-55° to +105°C
Termination Interface Style	Through Hole - Compliant Pin

Solder Process Data

Lead-Free Process Capability	N/A
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